Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-10-15
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	Floriana San Biagio	Representative Title	AMS Materials Declaration Champion
Representative Phone *	Refer to " Supplier Comment" section	Representative Email *	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LM2903WHYST	EBE3*0193AFY	A	ZY1A	2015-10-15
	Amount	UoM	Unit type	ST ECOPACK Grade
	23.70	mg	Each	ECOPACK® 3
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3X3X0.86	8	gull wing	
Comment	Package: E3 MSOP/TSSOP 8 BODY3.00 PITCH0.65			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList : REACH-15th June 2015				
Query				**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						**Mfr Item Name**	**EBE3*0193AFY**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	Other inorganic materials	0.785	mg	supplier	die	Silicon (Si)	7440-21-3		0.772	mg	983439	32574
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	7643	253
Die				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.003	mg	3822	127
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.004	mg	5096	169
Leadframe	Copper & its alloys	9.583	mg	supplier	alloy	Copper (Cu)	7440-50-8		9.035	mg	942815	381224
Leadframe				supplier	alloy	Nickel (Ni)	7440-02-0		0.282	mg	29427	11899
Leadframe				supplier	alloy	Silicon (Si)	7440-21-3		0.061	mg	6365	2574
Leadframe				supplier	alloy	Magnesium (Mg)	7439-95-4		0.014	mg	1461	591
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.185	mg	19305	7806
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.004	mg	417	169
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.002	mg	209	84
Die attach	Other inorganic materials	0.336	mg	supplier	glue	Epoxy resin A	9003-36-5		0.023	mg	68452	970
Die attach				supplier	glue	Epoxy resin B	68475-94-5		0.014	mg	41667	591
Die attach				supplier	glue	Silver(Ag)	7440-22-4		0.257	mg	764881	10844
Die attach				supplier	glue	Lactone	96-48-0		0.014	mg	41667	591
Die attach				supplier	glue	Polyoxypropylenediamine	9046-10-0		0.014	mg	41667	591
Die attach				supplier	glue	2,6-Diglycidyl phenyl allyl ether oligomer	proprietary		0.014	mg	41667	591
Bonding wire	Precious metals	0.07	mg	supplier	wire	Gold (Au)	7440-57-5		0.07	mg	1000000	2954
encapsulation	Other inorganic materials	12.922	mg	supplier	mold compound	Epoxy Resin	proprietary		1.163	mg	90002	49072
encapsulation				supplier	mold compound	Silica fused (SiO2)	60676-86-0		10.854	mg	839963	457975
encapsulation				supplier	mold compound	Phenol Resin	Trade secret		0.841	mg	65083	35485
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		0.064	mg	4953	2700